LINEAR TECHNOLOGY MATERIALS DECLARATION

lt1997hms-1#trpbf **(Engineering Calculation)** **MSOP with 4 PINS REMOVED**

(printed on: 2020-07-11 16:31:51) **TOTAL MASS (g): 0.038119**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.003937**	**1000000**	**103281.757812**
Die Coat	Dow Corning	Silicone	69430-27-9	**0.000000**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013845	975000	363204.46875
		Iron (Fe)	7439-89-6	0.000341	24000	8945.6640625
		Phosphorus (P)	7723-14-0	0.000004	300	104.93447876
		Zinc (Zn)	7440-66-6	0.000010	700	262.336181641
		Nickel (Ni)	7440-02-0	0.000000	0	0
		Silicon (Si)	7440-21-3	0.000000	0	0
		Magnesium (Mg)	7439-95-4	0.000000	0	0
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead Frame Total:		**0.014200**	**1000000**	**372517.40625**
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
		Exter. Plating Sn	7440-31-5	0.000710	1000000	18626.5234375
		External Plating Total:		**0.000710**	**1000000**	**18626.5234375**
		Inter. Plating Ni	7440-02-0	0.000000	0	0
		Inter. Plating Ag	7440-22-4	0.000086	1000000	2256.09130859
		Internal Plating Total:		**0.000086**	**1000000**	**2256.09130859**
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0
		Tin (Sn)	7440-31-5	0.000000	0	0
		Lead (Pb)	7439-92-1	0.000000	0	0
		Silica (SiO2)	60676-86-0	0.000012	50000	314.803436279
		Indium (In)	7440-74-6	0.000000	0	0
		Metal Oxide		0.000074	300000	1941.2878418
		Antimony (Sb)	7440-36-0	0.000000	0	0
		Resin (EP)		0.000161	650000	4223.61279297
		Die Attach Total:		**0.000247**	**1000000**	**6479.70361328**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001932	103000	50683.3515625
		Bromine (Br)	40039-93-8	0.000000	0	0
		Silica (SiO2)	60676-86-0	0.016790	895000	440462.5
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0
		Metal Hydroxide		0.000000	0	0
		Carbon Black (C)	1333-86-4	0.000038	2000	996.877441406
		Encapsulation Total:		**0.018760**	**1000000**	**492142.6875**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.000179**	**1000000**	**4695.81787109**
					TOTAL MASS (g):	**0.038119**